



P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|------------------------------------|------------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}$ (Ω) | I _D (A) ^{a, e} | Q _g (Typ.) | | | |
| - 30 | 0.042 at V _{GS} = - 10 V | - 6 | 7 nC | | | |
| - 30 | 0.072 at V _{GS} = - 4.5 V | - 6 | 7 110 | | | |

FEATURES

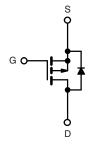
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



FREE

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch



P-Channel MOSFET

| | SO-8 | _ |
|-----|----------|-----|
| S 1 | | 8 D |
| S 2 | | 7 D |
| S 3 | | 6 D |
| G 4 | | 5 D |
| | Top View | |

Ordering Information: Si4485DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

| Parameter | | Symbol | Limit | Unit | |
|--|-----------------------------------|-----------------|-----------------------|------|--|
| Drain-Source Voltage | | V _{DS} | - 30 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| | T _C = 25 °C | | - 6 ^e | | |
| Continuous Prain Current (T = 150 °C) | T _C = 70 °C | | - 6 ^e | | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | I _D | - 5.9 ^{b, c} | | |
| | T _A = 70 °C | | - 4.7 ^{b, c} | Α | |
| Pulsed Drain Current | | I _{DM} | - 25 | | |
| Continous Source-Drain Diode Current | T _C = 25 °C | 1 | - 4.2 | | |
| Continues Source-Drain Diode Current | T _A = 25 °C | ls - | - 2 ^{b, c} | | |
| | T _C = 25 °C | | 5 | | |
| Maximum Power Dissipation | T _C = 70 °C | ь | 3.2 | W | |
| | T _A = 25 °C | P _D | 2.4 ^{b, c} | VV | |
| | T _A = 70 °C | | 1.5 ^{b, c} | | |
| Operating Junction and Storage Temperature | T _J , T _{stg} | - 55 to 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|----------|------------|---------|------|--------------|--|--|
| Parameter | Symbol | Typical | Maximum | Unit | | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 s | R_{thJA} | 42 | 53 | °C/W | | |
| Maximum Junction-to-Foot (Drain) Steady State | | R_{thJF} | 19 | 25 | O/ VV | | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 °C/W.
- e. Package Limited.

Si4485DY

Vishay Siliconix



| SPECIFICATIONS $T_J = 25 ^{\circ}C$, Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|-------------------------|---|-------|-------|--------|-------|--|
| Static | Cymbol | rest conditions | | iyp. | IVIAA. | 01111 | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = - 250 μA | - 30 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | | | - 19 | | mV/°C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = - 250 μA | | 4.4 | | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_{D} = -250 \mu A$ | - 1.2 | | - 2.5 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| <u> </u> | | V _{DS} = - 30 V, V _{GS} = 0 V | | | - 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C | | | - 5 | μΑ | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$ | - 25 | | | Α | |
| | | V _{GS} = - 10 V, I _D = - 5.9 A | | 0.035 | 0.042 | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 4.5 A | | 0.060 | 0.072 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 5.9 A | | 10 | | S | |
| Dynamic ^b | | | | • | • | | |
| Input Capacitance | C _{iss} | | | 590 | | | |
| Output Capacitance | C _{oss} | V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz | | 115 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | 1 | | 93 | | | |
| Total Cata Chavas | Qg | V _{DS} = -15 V, V _{GS} = -10 V, I _D = -5.9 A | | 13.6 | 21 | nC | |
| Total Gate Charge | | | | 7 | 11 | | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5.9 \text{ A}$ | | 2.3 | | | |
| Gate-Drain Charge | Q_{gd} | | | 3.2 | | | |
| Gate Resistance | R_g | f = 1 MHz | 1 | 5 | 10 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 30 | 45 | | |
| Rise Time | t _r | V_{DD} = - 15 V, R_L = 3.2 Ω | | 25 | 38 | ns | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -4.7 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$ | | 16 | 24 | | |
| Fall Time | t _f | | | 8 | 16 | | |
| Turn-On Delay Time | t _{d(on)} | | | 8 | 16 | | |
| Rise Time | t _r | V_{DD} = - 15 V, R_L = 3.2 Ω | | 10 | 20 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -4.7 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$ | | 18 | 27 | | |
| Fall Time | t _f | | | 8 | 16 | | |
| Drain-Source Body Diode Characteristi | cs | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 4.2 | Α | |
| Pulse Diode Forward Current | I _{SM} | | | | - 25 | | |
| Body Diode Voltage | V_{SD} | I _S = - 4.7 A, V _{GS} = 0 V | | - 0.8 | - 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 17 | 26 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | I _F = - 4.7 A, dI/dt = 100 A/μs, T _J = 25 °C | | 9 | 18 | nC | |
| Reverse Recovery Fall Time | t _a | 1 = -4.7 A, αι/αι = 100 A/μs, 1 J = 25 °C | | 10 | | | |
| leverse Recovery Rise Time t _b | |] | | 7 | | ns | |

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

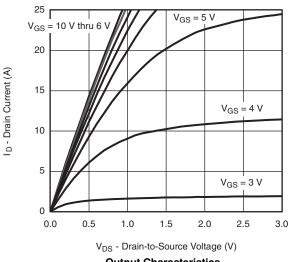
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

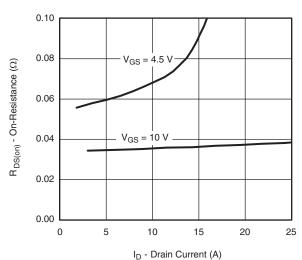




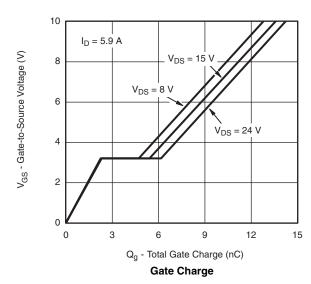
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

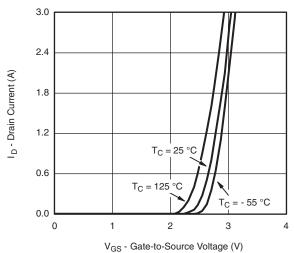




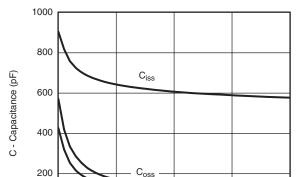


On-Resistance vs. Drain Current





Transfer Characteristics



 $\mathsf{C}_{\mathsf{rss}}$

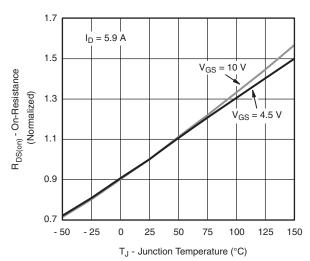
5

0

0

10 V_{DS} - Drain-to-Source Voltage (V)

Capacitance



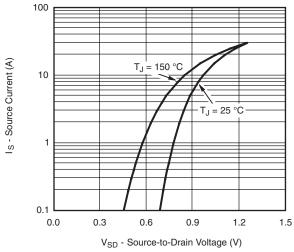
On-Resistance vs. Junction Temperature

20

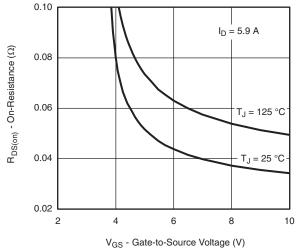
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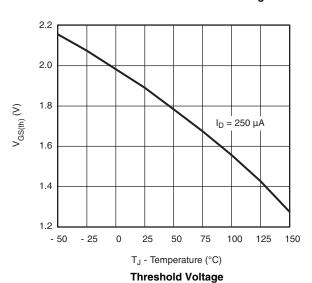
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

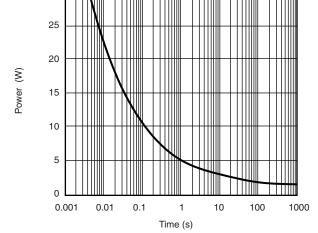


Source-Drain Diode Forward Voltage



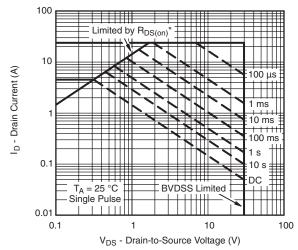
On-Resistance vs. Gate-to-Source Voltage





30

Single Pulse Power (Junction-to-Ambient)

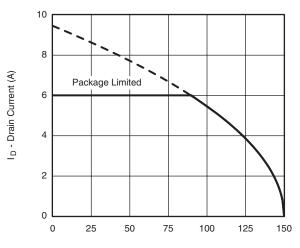


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

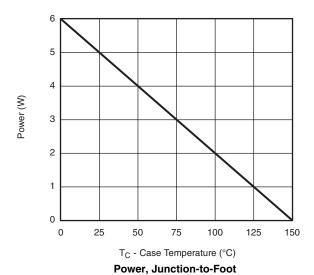


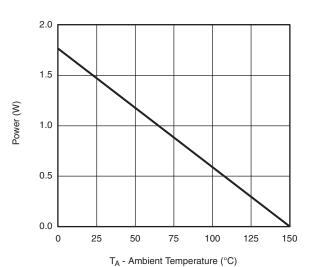
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 T_C - Case Temperature (°C)

Current Derating*





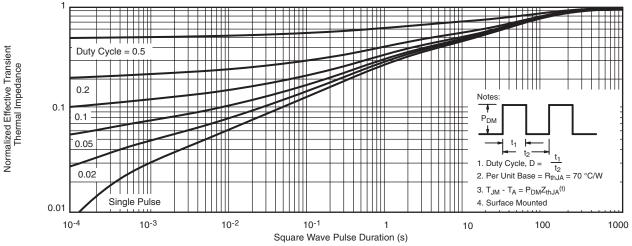
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

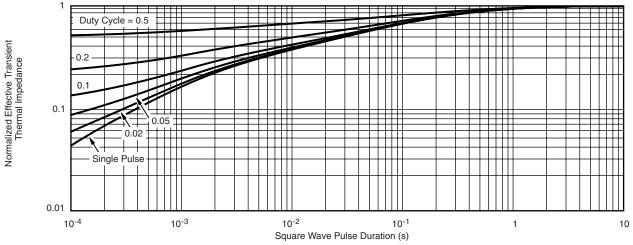
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







| | MILLIMETERS | | INCHES | | |
|--------------------------------|-------------|------|-----------|-------|--|
| DIM | Min | Max | Min | Max | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | |
| е | 1.27 | BSC | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | |
| q | 0° | 8° | 0° | 8° | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | |
| ECN: C-06527-Rev. I. 11-Sep-06 | | | | | |

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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